

FMI06N60ES

FUJI POWER MOSFET

Super FAP-E^{3S} series

N-CHANNEL SILICON POWER MOSFET

■ Features

Maintains both low power loss and low noise Lower R_{DS}(on) characteristic More controllable switching dv/dt by gate resistance Smaller V_{GS} ringing waveform during switching Narrow band of the gate threshold voltage (3.7±0.5V) High avalanche durability

Applications

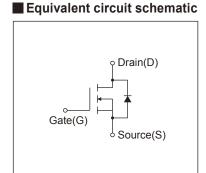
Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

Maximum Ratings and Characteristics

● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

	<u> </u>
T-Pack(L) 10 % 5	4.5±0.2
2	_, _1,3±0,2
0.9±0.3	Fig. 1. (See Notes)
Trodemark	(See Notes)
Type name	_Fig. 1.
Lot No.	1 1 / 1/2
	Solder Plating is
₩ ₩ ₩ 	Plating (S)
3,6 ± 0.2 13,5 min.	Solder Plating to the sold to
1 1 1 1 1 1 1 1	***************************************
0 0 0	
0 0 0	11 '''
0.82;7	0.4*3;7
2.54±0.2 2.54±0.2	2.7±0.2
	CONNECTION
+ + +	① GATE
000	② DRAIN ③ SOURCE
300	O 555.152

■ Outline Drawings [mm]



Description	Symbol	Characteristics	Unit	Remarks
Drain Sauras Valtara	V _{DS}	600	V	
Drain-Source Voltage	VDSX	600	V	V _{GS} = -30V
Continuous Drain Current	ID	±6	Α	
Pulsed Drain Current	IDP	±24	Α	
Gate-Source Voltage	V _{GS}	±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	IAR	6	Α	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	313.7	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	10.5	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	3.8	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Maximum Power Dissipation	PD	1.67	W	Ta=25°C
		105	VV	Tc=25°C
Operating and Storage Temperature range	Tch	150	°C	
	Tstg	-55 to +150	°C	

● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit	
Drain-Source Breakdown Voltage	BVDSS	I _D =250μA, V _{GS} =0V		600	-	-	V	
Gate Threshold Voltage	V _{GS} (th)	I _D =250µA, V _{DS} =V _{GS}		3.2	3.7	4.2	V	
Zero Gate Voltage Drain Current		V _{DS} =600V, V _{GS} =0V	T _{ch} =25°C	-	-	25		
	IDSS	V _{DS} =480V, V _{GS} =0V	T _{ch} =125°C	-	-	250	μA	
Gate-Source Leakage Current	Igss	V _{GS} =±30V, V _{DS} =0V		-	10	100	nA	
Drain-Source On-State Resistance	Ros (on)	I _D =3A, V _{GS} =10V		-	1.03	1.20	Ω	
Forward Transconductance	g fs	I _D =3.0A, V _{DS} =25V		2.5	5	-	S	
Input Capacitance	Ciss	V _{DS} =25V		-	950	1425	pF	
Output Capacitance	Coss	V _{GS} =0V	V _{GS} =0V		100	150		
Reverse Transfer Capacitance	Crss	f=1MHz		-	7.5	11		
Turn-On Time	td(on)	V _{cc} =300V V _{ss} =10V I _D =3.0A R _G =27Ω		-	29	43.5	ns	
Turn-On Time	tr			-	15	22.5		
Trum Off Time	td(off)			-	75	113		
Turn-Off Time	tf			-	16	24		
Total Gate Charge	Q _G	1/ 0001/	V _{cc} =300V I _D =6A V _{cc} =10V		31	46.5		
Gate-Source Charge	QGS				10.5	15.8	nC	
Gate-Drain Charge	Q _{GD}	V _{GS} =10V			8	12		
Gate-Drain Crossover Charge	Qsw	VGS-10V		-	4.5	6.75		
Avalanche Capability	lav	L=6.39mH, T _{ch} =25°C		6	-	-	А	
Diode Forward On-Voltage	V _{SD}	I _F =6A, V _{GS} =0V, T _{ch} =25°C	I _F =6A, V _{GS} =0V, T _{ch} =25°C		0.90	1.35	V	
Reverse Recovery Time	trr	I _F =6A, V _{GS} =0V	I _F =6A, V _{GS} =0V		0.4	-	μS	
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25	°C	-	3.3	-	μC	

Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to case			1.19	°C/W
	Rth (ch-a)	Channel to ambient			75.0	°C/W

Note *1 : Tch≤150°C

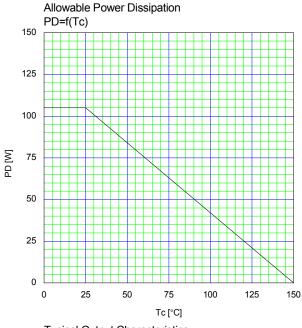
Note *2: Stating Tch=25°C, Ias=2.4A, L=99.8mH, Vcc=60V, Rc=50Ω
Eas limited by maximum channel temperature and avalanche current.
See to 'Avalanche Energy' graph.

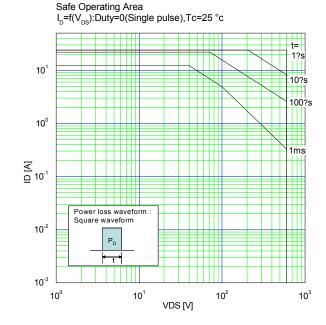
Note $^{\star}3$: Repetitive rating : Pulse width limited by maximum channel temperature

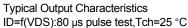
See to the 'Transient Themal impeadance' graph.

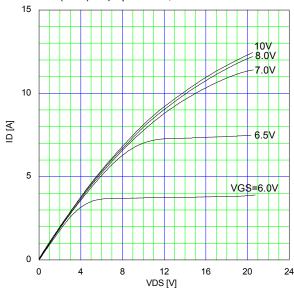
Note *4 : I₅≤-I₀, -di/dt=100A/μ₅, Vcc≤BV₀ss, Tch≤150°C.

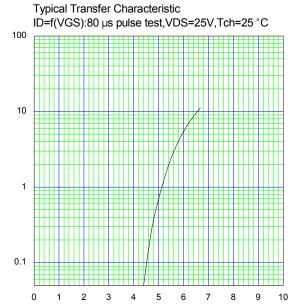
Note *5 : I₅≤-I₀, dv/dt=3.8kV/μ₅, Vcc≤BV₀ss, Tch≤150°C.



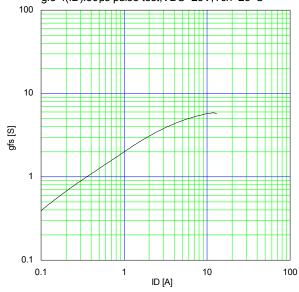


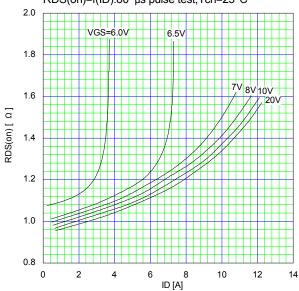






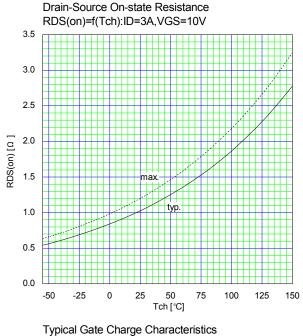
Typical Transconductance gfs=f(ID):80µs pulse test,VDS=25V,Tch=25°C

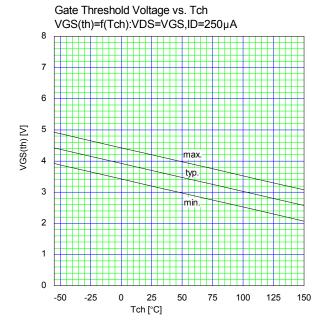


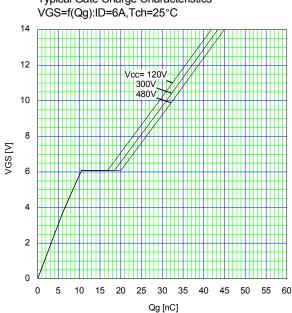


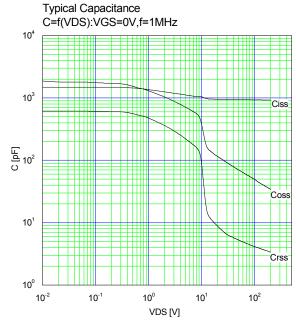
Typical Drain-Source on-state Resistance RDS(on)=f(ID):80 µs pulse test,Tch=25°C

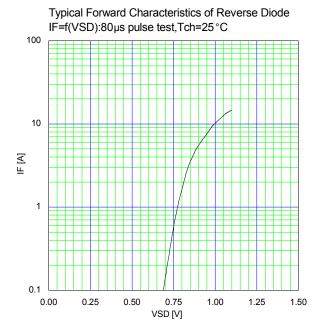
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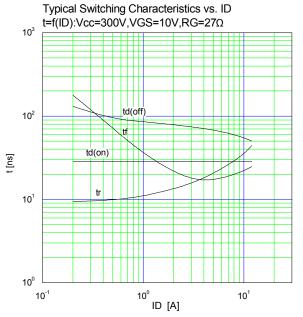


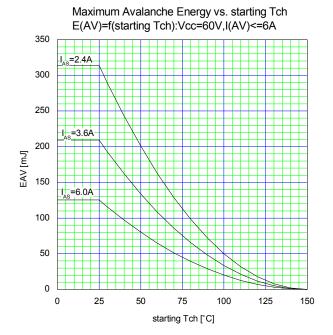


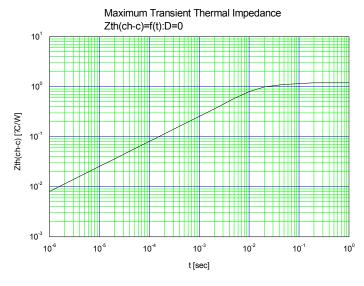












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- OA equipment

Audiovisual equipment

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